

Amendment history of SSD1351 Specification

Revision	Description of any change	Issued	Effective
0.10 C6FA1 30-May-08	1 st draft Approver list: Product Marketing- Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Jimmy Chiu Quality & Manufacturing-Daniel Ho Test Engineering - Warren Wong	Johnkid Lo	10-Jun-08
1.0 C6FA2 11-Dec-08	<ol style="list-style-type: none"> 1. Change to Advance information 2. Add amendment history 3. Add U1 , U2, U3 dwg into appendix 4. Revise die thickness tolerance from $\pm 25\mu\text{m}$ to $\pm 15\mu\text{m}$ on Fig 5-1 & section 3 5. Remove “The typical regulated V_{DD} is about 2.5V” in section 8.10 & figure 14-1 6. Revise table 12-1 DC characteristic 7. Revise table 13-1,13-2,13-3,13-4,13-5 (V_{CI} range) AC characteristic 8. Remove V_{DD} range in Section 12 & 13 9. Revise command table for A0h, 96h, B2h 10. Revise V_{CC} voltage range from 10V-20V to 10V to 18V <ol style="list-style-type: none"> i. Section 2 Feature list ii. Section 8.6 SEG/COM Driving block iii. Section 11 Maximum rating iv. Section 12 DC characteristic v. Section 14 Application example 11. Revise typo in Table 6-1: SSD1351UR1 Pin Assignment Table Approver list: Product Marketing- Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Johnkid Lo Quality & Manufacturing-Kenneth Ho Test Engineering - Stephen Leung	Ada Ng	12-Dec-08
1.1 C6FA2 19-Feb-09	<ol style="list-style-type: none"> 1 Revised Section 8.1 MCU interface <ol style="list-style-type: none"> 1.1 Revise Figure 8-2 & 8-3 : from D[7:0] to D[17:0] 1.2 Revise Section 8.1.3 & 8.1.4, Figure 8-5, Figure 8-6, Figure 13-3, Figure 13-4 : From “RW acts as SCLK, D0 acts as SDIN” to “D0 acts as SCLK, D1 acts as SDIN” 2 Revised Note (5) of Figures 8-13 & 8-14 on P.30 3 Add SSD1351U4R1 in appendix. Approver list: Product Marketing- Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Johnkid Lo Quality & Manufacturing- Daniel Ho Test Engineering - Stephen Leung	Ada Ng	19-Feb-09

Revision	Description of any change	Issued	Effective
1.2 C6FA2 C6FA3 27-Aug-09	<ol style="list-style-type: none"> 1 Change “Gold Bump Die” to “COG” for SSD1351Z in Table 3-1 Ordering information 2 Revise typo in Figure 5 1: SSD1351Z Die Drawing (position of L, T alignment mark) 3 Revise pin description of VSL pin 4 Revise typo in P.45 : 10.1.9 Set Function selection (ABh) 5 Add Note 2 in application example Fig 14-1. 6 Add SSD1351U5R1 in appendix. V (date back) 7 Add Command B2h into appendix VI <p>Approver list: Product Marketing- Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Johnkid Lo Quality & Manufacturing- Daniel Ho Test Engineering - PL Che</p>	Ada Ng	31-Aug-09
1.3 C6FA2 C6FA3 21-Oct-09	<ol style="list-style-type: none"> 1 Added +/- 0.05mm tolerance for Die Size (after sawing) in Section 5 – P.9 2 Added command C1h in the description of command FDh – P.37 3 Revised typo error on the description of command C1h – P.46 4 Updated the $I_{SLP\ VCI}$ sleep mode current section of Table 12-1 (Max = 50uA when internal V_{DD} is enabled) – P.49 5 Revised disclaimer 6 Date back the edition of Appendix 1.3 (for command B2h) <p>Approver list: Marketing – Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Johnkid Lo PQA – Daniel Ho Test Engineering – Stephen Leung</p>	Ada Ng	28-Oct-09

SSD1351

Advance Information

128 RGB x 128 Dot Matrix
OLED/PLED Segment/Common Driver with Controller

This document contains information on a new product. Specifications and information herein are subject to change without notice.

<http://www.solomon-systech.com>

SSD1351

Rev 1.3

P 1/58

Oct 2009

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Appendix: IC Revision history of SSD1351 Specification

Version	Change Items	Effective Date
0.10	1. 1 st release	10-Jun-08
1.0	<ol style="list-style-type: none"> 1. Change to Advance Info 2. Revise die thickness tolerance from $\pm 25\mu\text{m}$ to $\pm 15\mu\text{m}$ 3. Revise table 12-1 DC characteristic 4. Revise tables 13 AC characteristic 5. Revise command table 6. Revise V_{CC} voltage range 	12-Dec-08
1.1	1. Revised section 8.1 MCU interface	19-Feb-09
1.2	<ol style="list-style-type: none"> 1 Change “Gold Bump Die” to “COG” for SSD1351Z in Table 3-1 Ordering information 2 Revise typo in Figure 5 1: SSD1351Z Die Drawing (position of L, T alignment mark) 3 Revise typo in P.45 : 10.1.9 Set Function selection (ABh) 4 Add Note 2 in application example Fig 14-1 	31-Aug-09
1.3	<ol style="list-style-type: none"> 1 Added +/- 0.05mm tolerance for Die Size (after sawing) in Section 5 – P.9 2 Added command C1h in the description of command FDh – P.37 3 Revised typo error on the description of command C1h – P.46 4 Updated the $I_{SLP_{VCI}}$ sleep mode current section of Table 12-1 (Max = 50uA when internal V_{DD} is enabled) – P.49 5 Revised declaimer 	28-Oct-09

